



## Final Product Change Notification

202204008F01 : LPC82x LPC83x Revision Change to 1B

**Note:** This notice is NXP Company Proprietary.

**Issue Date:** May 06, 2022 **Effective date:** Aug 04, 2022

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### Management summary

Microcontroller products LPC82x and LPC83x will be sourced from the new product revision "1B" to resolve the BOD.1 errata.

### Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input checked="" type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input checked="" type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware	<input type="checkbox"/> Other			

## PCN Overview

### Description

Microcontroller products LPC82x and LPC83x will be sourced from the new product revision "1B".

- This design change fixes the BOD.1 errata as documented in the device errata sheet updates.

- The following errata sheets have been updated with the BOD.1 errata:

LPC82x errata sheet has been updated to rev 1.4,

[https://www.nxp.com/docs/en/errata/ES\\_LPC82X.pdf](https://www.nxp.com/docs/en/errata/ES_LPC82X.pdf)

LPC83x errata sheet has been updated to rev 1.2,

[https://www.nxp.com/docs/en/errata/ES\\_LPC83X.pdf](https://www.nxp.com/docs/en/errata/ES_LPC83X.pdf)

- The design change has no reliability impact.

### Reason

- To fix the BOD.1 functional deviation as documented in the errata sheets.

### Identification of Affected Products

Top Side Marking

The last character of the last line of the device top side marking changes from "A" to "B"

### Product Availability

**Sample Information**

Samples are available from May 11, 2022

**Production**

Planned first shipment Aug 04, 2022

**Anticipated Impact on Form, Fit, Function, Reliability or Quality**

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The design change resolved the BOD.1 errata described in the errata sheets.

**Data Sheet Revision**

No impact to existing datasheet

**Disposition of Old Products**

Existing inventory will be shipped until depleted

**Additional information**

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Self qualification: [view online](#)

Additional documents: [view online](#)

**Timing and Logistics**

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In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Jun 05, 2022.

**Contact and Support**

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For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

<b>Name</b>	Tim Camenzind
<b>Position</b>	Quality Manager
<b>e-mail address</b>	tim.camenzind@nxp.com

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NXP Semiconductors  
High Tech Campus, 5656 AG Eindhoven, The Netherlands



Changed Orderable Part#	12NC	Product Type	Product Description	Package Outline	Package Description	Product Status	Customer Specific Indicator	Product Line
LPC822M101JDH20J	935304005118	LPC822M101JDH20	32-bit ARM M0+	(T)SSOP20	SOT360-1	RFS	No	BLM1
LPC824M201JDH20J	935304006118	LPC824M201JDH20	32-bit ARM M0+	(T)SSOP20	SOT360-1	RFS	No	BLM1
LPC822M101JHI33Y	935304007518	LPC822M101JHI33	32-bit ARM M0+	H(V)QFN32WF	SOT617-3	RFS	No	BLM1
LPC822M101JHI33E	935304007551	LPC822M101JHI33	32-bit ARM M0+	H(V)QFN32WF	SOT617-3	RFS	No	BLM1
LPC822M101JHI33K	935304007557	LPC822M101JHI33	32-bit ARM M0+	H(V)QFN32WF	SOT617-3	RFS	No	BLM1
LPC824M201JHI33Y	935304008518	LPC824M201JHI33	32-bit ARM M0+	H(V)QFN32WF	SOT617-3	RFS	No	BLM1
LPC824M201JHI33E	935304008551	LPC824M201JHI33	32-bit ARM M0+	H(V)QFN32WF	SOT617-3	RFS	No	BLM1
LPC824M201JHI33K	935304008557	LPC824M201JHI33	32-bit ARM M0+	H(V)QFN32WF	SOT617-3	RFS	No	BLM1
LPC824HI33/CP3390K	935430087557	LPC824HI33/CP3390	32-bit ARM M0+	H(V)QFN32WF	SOT617-3	RFS	No	BLM1
LPC834M101FHI33Y	935309056518	LPC834M101FHI33	32-bit ARM M0	H(V)QFN32WF	SOT617-3	RFS	No	BLM1
LPC832M101FDH20FP	935309057129	LPC832M101FDH20	32-bit ARM M0	(T)SSOP20	SOT360-1	RFS	No	BLM1